



Material Content Data Sheet



Sales Product Name		TLE4963-2M		Issued		24. August 2015			
MA#		MA001106126							
Package		PG-SOT23-3-15		Weight*		9.78 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.220	2.25	2.25	22463	22463	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		74		
		non noble metal	titanium	7440-32-6	0.004	0.04		369	
		non noble metal	chromium	7440-47-3	0.011	0.11		1106	
wire	noble metal	non noble metal	copper	7440-50-8	3.590	36.72	36.88	367219	368768
		noble metal	gold	7440-57-5	0.023	0.24	0.24	2355	2355
		organic material	carbon black	1333-86-4	0.055	0.56		5619	
encapsulation	plastics	epoxy resin	-	1.181	12.08		120813		
		inorganic material	silicondioxide	60676-86-0	4.257	43.55	56.19	435491	561923
leadfinish	non noble metal	tin	7440-31-5	0.150	1.53	1.53	15308	15308	
plating	noble metal	silver	7440-22-4	0.149	1.52	1.52	15200	15200	
glue	plastics	epoxy resin	-	0.024	0.24		2447		
		noble metal	silver	7440-22-4	0.113	1.15	1.39	11536	13983
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

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